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CUSTOMER'S CODE PAN172x / PAN171x	PANASONIC'S CODE ENW89820AxKF / ENW		DATE	08.07.20)15			
Product Specification								
Applicant / Manufacturer Hardware	Panasonic Industria Zeppelinstrasse 19 21337 Lüneburg Germany		urope GmbH					
Applicant / Manufacturer Software	Please refer to cha Software Versions	oter 24 / 24.1	I Information rega	arding				
Software Version	Please refer to cha Software Versions	oter 24 / 24.1	I Information rega	arding				
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1. SCOPE OF THIS DOCUMEN	Т					
	s to Panasonic's, Class 2, Bluetooth® ¹ lo <u>40 from Texas Instruments</u>) and PAN172			ıle,		
2. DIFFERENCE PAN1720 / PA	N1721					
Both the PAN1720 and PAN1721	1 are refered to as the PAN172x in this c	document.				
communication interface on the F PAN1721. Compared to the PAN	with the PAN1720, with the exception the PAN1720 and I2C is the hardware comm I1720, the PAN1721 provides lower RF of found on the PAN1720, and provides lo	nunication inte current consu	erface on the Imption. The PA			
Additional details , which have an Instruments.	n impact on the module can be found in t	the datasheet	ts from Texas			
CC2540 from Texas Instruments						
CC2541 from Texas Instruments						
3. DIFFERENCE PAN172X / PA	the CC2541 come with an internal 256 k N171X na version where the PAN172x are the v					
 Bluetooth Low Energy Single Mode 4.0 Surface mount type 15.6 x 8.7 x 1.8 mm³ Up to 4.0 dBm Tx power (typical) with transmit power control CC2541 has typically 0dBm Tx power High sensitivity (-94 dBm typ.) Texas Instrument's CC2540/CC2541 Single Chip BLE Solution inside High performance low power 8051 Microcontroller core No external components needed Fast Connection Setup Internal crystal oscillator (32MHz) Internal 32khz crystal oscillator for Sleep Timer Two powerful USARTs UART, USB or I2C interface Powerful five channel DMA Latest Profiles included e.g. Battery Monitor and Temperature sensor Integrated shielding to resist EMI Manufactured in conformance with RoHS 						
¹ Bluetooth is a registered tradem	ark of the Bluetooth Special Interest Gro	oup.				

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BLUETOOTH LOW ENERGY

Bluetooth Low Energy (BLE), part of Bluetooth Ver. 4.0, specifies two types of implementation: Single mode and dual mode. Single mode devices implement the low energy specification and consume just a fraction of the power of classic Bluetooth, allowing the short-range wireless standard to extend to coin cell battery applications for the first time. Dual mode devices combine low energy with the power of classic Bluetooth and are likely to become a de facto feature in almost all new Bluetooth enabled cellular phones and computers.

Single mode Bluetooth 4.0 Low Energy is not backwards compatible with previous Bluetooth standards. Dual mode Bluetooth 4.0 Low Energy is backwards compatible and well suited for gateway applications, but is not practical for low power devices.



5. APPLICATIONS FOR THE MODULE

All Embedded Wireless Applications

- Access Points
- Industrial Control
- Medical
- Scanners
- Wireless Sensors
- Low Power

- Proximity
- Smart Phone
- Access Points
- Temperature
- Wellness
- Sports

6. DESCRIPTION FOR THE MODULE

The PAN172x is a short-range, Class 2, BLE single mode module for implementing Bluetooth functionality into various electronic devices. A block diagram can be found in chapter 9.

The PAN172x is a cost-effective, low-power, true system-on-chip (SoC) for Bluetooth low energy applications. It enables robust BLE master or slave nodes to be built with very low total bill-of-material costs. The PAN172x combines an excellent RF transceiver with an industry-standard enhanced 8051 MCU, in-system programmable flash memory, 8-KB RAM, and many other powerful supporting features and peripherals. The PAN172x is suitable for systems where very low power consumption is required. Very low-power sleep modes are available. Short transition times between operating modes further enable low power consumption.

Panasonic offers Bluetooth low energy protocol stacks and applications from Texas Instruments and BlueRadios. The Bluetooth low energy protocol stack from Texas Instruments, is a flexible and cost-effective single-mode Bluetooth low energy solution.

The BlueRadios stack enables rapid and low cost development using an AT command set without the need for a complier. Additional advantages include UART programming, over-the-air-updates, easy integration "C" library framework, serial streaming of data, and smart phone libraries and applications.

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Please contact your local sales o www.panasonic.com/rfmodules f	u/i/29606/wireless_modules/wireless_m	ions and service	
7.1. PAN172X TERMINAL L	AYOUT		
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	s marked with a blue circle.		
Top View, Application P	15.6 mm		
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	E4) E5 E6 E7 E8 E9	_ _	
		1.2	8.70 mm
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	A4 A5 A6 A7 A8 A9		
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No	Pin Name	Pin Type	Description
A1	GND	Ground Pin	Connect to Ground
A2	P1.0	Digital I/O	Port 1.0 – 20mA drive capability
A3	Reset	Digital Input	Reset, active-low
A4	VCC	Power	2V – 3.6V analog/digital power supply connection
A5	VCC	Power	2V – 3.6V analog/digital power supply connection
A6	VCC	Power	2V – 3.6V analog/digital power supply connection
A7	GND	Ground Pin	Connect to Ground
A8	NC		Not Connected
A9	GND	Ground Pin	Connect to Ground
A11	GND	Ground Pin	Connect to Ground
A12	GND	Ground Pin	Connect to Ground
B1	P1.3	Digital I/O	Port 1.3
B2	P1.2	Digital I/O	Port 1.2
B3	P1.1	Digital I/O	Port 1.1 – 20mA drive capability
B4	P0.6	Digital I/O	Port 0.6
B5	NC	Digital I/O	Not Connected
B5 B6	P0.1	Digital I/O	Port 0.1
<u>во</u> В7	P0.1	Digital I/O	Port 0.0
	NC		Not Connected
B8			
B9	NC NC		Not Connected
C1	NC P1.4	Digital I/O	Not Connected
C2		Digital I/O	Port 1.4 / BR-SW UART CTS
C3	P1.5	Digital I/O	Port 1.5 / BR-SW UART RTS
C4	P0.7	Digital I/O	Port 0.7
C5	NC		Not Connected
<u>C6</u>	NC		Not Connected
C7	NC		Not Connected
C8	GND	Ground Pin	Connect to Ground
C9	GND	Ground Pin	Connect to Ground
D1	DVDD_USB	Power (digital)	2V – 3.6V digital power supply connection
D2	USB_N	Digital I/O	USB N / PAN17x1 I2C SDA // Leave floating if not used
D3	USB_P	Digital I/O	USB P / PAN17x1 I2C SCL // Leave floating if not used
D4	NC		Not Connected
D5	NC		Not Connected
D6	NC		Not Connected
D7	GND	Ground Pin	Connect to Ground
D8	GND	Ground Pin	Connect to Ground
D9	NC/RF		PAN172x Not Connected/50 ohm RF_Out PAN171x
E1	P2.1/DD	Digital I/O	Port 2.1 / Programming Interface DD
E2	P2.2/DC	Digital I/O	Port 2.2 / Programming Interface DC
E3	DGND_USB	Ground Pin	Connect to Ground
E4	NC		Not Connected
E5	NC		Not Connected
E6	P0.2/RX/MISO	Digital I/O	Port 0.2 / TI-SW UART RX / SPI MISO
E7	NC		Not Connected
E8	GND	Ground Pin	Connect to Ground
E9	GND	Ground Pin	Connect to Ground
F1	GND	Ground Pin	Connect to Ground
F2	P1.6	Digital I/O	Port 1.6 / BR-SW UART TX
F3	P1.7	Digital I/O	Port 1.7 / BR-SW UART RX
F4	P2.0	Digital I/O	Port 2.0
F5	P0.4/CTS/CS	Digital I/O	Port 0.4 / TI-SW UART CTS / SPI CS
F6	NC		Not Connected
F7	P0.3/TX/MOSI	Digital I/O	Port 0.3 / TI-SW UART TX /SPI MOSI
F8	P0.5/RTS/CLK	Digital I/O	Port 0.5 / TI-SW UART RTS /SPI CLK
F9	GND	Ground Pin	Connect to Ground
F11			
F11 F12	GND GND	Ground Pin Ground Pin	Connect to Ground Connect to Ground

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CUSTOMER'S CODE PAN172x / PAN171x		PANASONIC'S CODE ENW89820AxKF / ENW89835AxKF	DATE	08.07.20)15

7.2. CROSSREFERENCE GPIO PAN-MODULE TO BLUERADIOS-MODULE

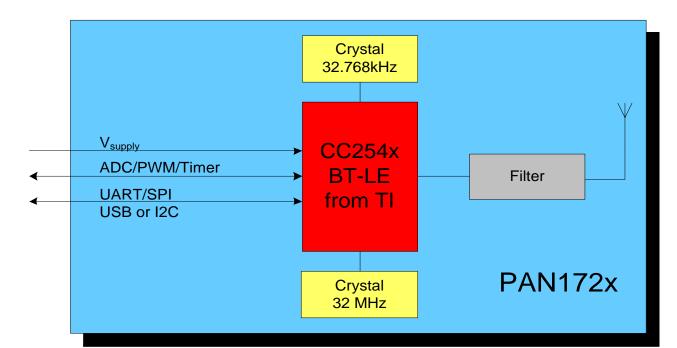
PAN	PAN17xx-BR		Radios
No	Pin Name	No	Pin Name
B7	P0.0	21	ADC_0
B6	P0.1	4	ADC_1
E6	P0.2 / MISO	5	SPI_MISO
F7	P0.3 / MOSI	8	SPI_MOSI
F5	P0.4 / CS	6	SPI_CSB
F8	P0.5 / CLK	7	SPI_CLK
B4	P0.6	26	PIO_3
C4	P0.7	25	PIO_6
A2	P1.0 GPIO	23	PIO_2
B3	P1.1 GPIO	24	PIO_5
B2	P1.2 GPIO	27	PIO_8
B1	P1.3 GPIO	22	PIO_9
C2	P1.4 / UART CTS	11	UART_CTS
C3	P1.5 / UART RTS	12	UART_RTS
F2	P1.6 GPIO / UART TXD	13	UART_TX
F3	P1.7 GPIO / UART RXD	14	UART_RX
F4	P2.0 GPIO	19	PIO_14
E1	P2.1 / DD	28	PIO_4
E2	P2.2 / DC	29	PIO_7

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SUBJECT	CLASS 2 BL SING	PAGE	9 of 3	37	
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8. BLUETOOTH FEATURES

- Bluetooth 4.0 single mode low energy technology.
- Class 2 TX power w/o external PA, improving link robustness.
- Excellent link budget (up to 96 dB), enabling long-range applications.
- Accurate digital received signal-strength indicator (RSSI)
- Integrates the new low power profiles and services
- Embedded BT-Stack available

9. PAN172X BLOCK DIAGRAM



CLASSIFICATION	PF	RODUCT SPECIFICATION	No. DS-17xx-2400-102		REV. 2.13
SUBJECT	CLASS 2 BLUETOOTH LOW ENERGY SINGLE MODE MODULE		PAGE 10 of 37		37
CUSTOMER'S COD PAN172x / PAN171x		PANASONIC'S CODE ENW89820AxKF / ENW89835AxKF	DATE	08.07.20)15

10. TEST CONDITIONS

Measurements shall be made under operating free-air temperature range unless otherwise specified.

Temperature	25 ± 10°C
Humidity	40 to 85%RH
Supply Voltage	3.3V

11. GENERAL DEVICE REQUIREMENTS AND OPERATION

All specifications are over temperature and process, unless indicated otherwise.

11.1. ABSOLUTE MAXIMUM RATINGS

No	See ²		Value	Unit
Rati	ngs Over Operati	ng Free-Air Temperature Range		
1	Supply voltage	All supply pins must have the same voltage	-0.3 to 3.9	V
2	Voltage on any o	ligital pin	-0.3 to VDD+0.3 <3,9	V
3	Operating ambie	ent temperature range	-40 to 85	°C
4	Storage tempera	ature range	-40 to 125	°C
5	Bluetooth RF inp	puts	10	dBm
6		ng to human-body model, JEDEC STD 22, method A114 arged-device model, JEDEC STD 22, method C101	1000 500	v

11.2. RECOMMENDED OPERATING CONDITIONS

No	Rating	Min	Max	Unit
1	Power supply voltage	2	3.6	V
2	Maximum ambient operating temperature	-40	85	°C

² Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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11.3. PAN1720 CURRENT CONSUMPTION

The current consumption is dependant on the user scenario and the setup and timing in the low power modes. The total power consumption can be optimized by adjusting the scan windows and intervals.

Please refer for the latest information for different power modes to the chapter "Electrical Characteristics" in Texas Instruments datasheet, refer to [2]. As indication below are typical values from CC2540 datasheet.

For PAN1721 refer to CC2541 datasheet.

ELECTRICAL CHARACTERISTICS

Measured on Texas Instruments CC2540 EM reference design with T_A = 25°C and VDD = 3 V

	PARAMETER	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
		Power mode 1. Digital regulator on; 16-MHz RCOSC and 32-MHz crystal oscillator off; 32.768-kHz XOSC, POR, BOD and sleep timer active; RAM and register retention		235		
I _{core}	Core current consumption	Power mode 2. Digital regulator off; 16-MHz RCOSC and 32-MHz crystal oscillator off; 32.768-kHz XOSC, POR, and sleep timer active; RAM and register retention		0.9		μA
		Power mode 3. Digital regulator off; no clocks; POR active; RAM and register retention		0.4		
		Low MCU activity: 32-MHz XOSC running. No radio or peripherals. No flash access, no RAM access.		6.7		mA
		Timer 1. Timer running, 32-MHz XOSC used		90		μA
		Timer 2. Timer running, 32-MHz XOSC used		90		μA
	Peripheral current consumption	Timer 3. Timer running, 32-MHz XOSC used		60		μA
^I peri	(Adds to core current I _{core} for each peripheral unit activated)	Timer 4. Timer running, 32-MHz XOSC used		70		μA
		Sleep timer, including 32.753-kHz RCOSC		0.6		μA
		ADC, when converting		1.2		mA

GENERAL CHARACTERISTICS

Measured on Texas Instruments CC2540 EM reference design with T_A = 25°C and VDD = 3 V

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
WAKE-UP AND TIMING					
Power mode 1 \rightarrow Active	Digital regulator on, 16-MHz RCOSC and 32-MHz crystal oscillator off. Start-up of 16-MHz RCOSC		4		μs
Power mode 2 or 3 \rightarrow Active	Digital regulator off, 16-MHz RCOSC and 32-MHz crystal oscillator off. Start-up of regulator and 16-MHz RCOSC		120		μs
Active \rightarrow TX or RX	Crystal ESR = 16 $\Omega.$ Initially running on 16-MHz RCOSC, with 32-MHz XOSC OFF		410		μs
	With 32-MHz XOSC initially on		160		μs
RX/TX turnaround			150		μs
RADIO PART		•			
RF frequency range	Programmable in 2-MHz steps	2402		2480	MHz
Data rate and modulation format	1 Mbps, GFSK, 250 kHz deviation				

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12. BLUETOOTH RF PERFORMANCE

12.1. PAN1720 BLUETOOTH CHARACTERISTICS

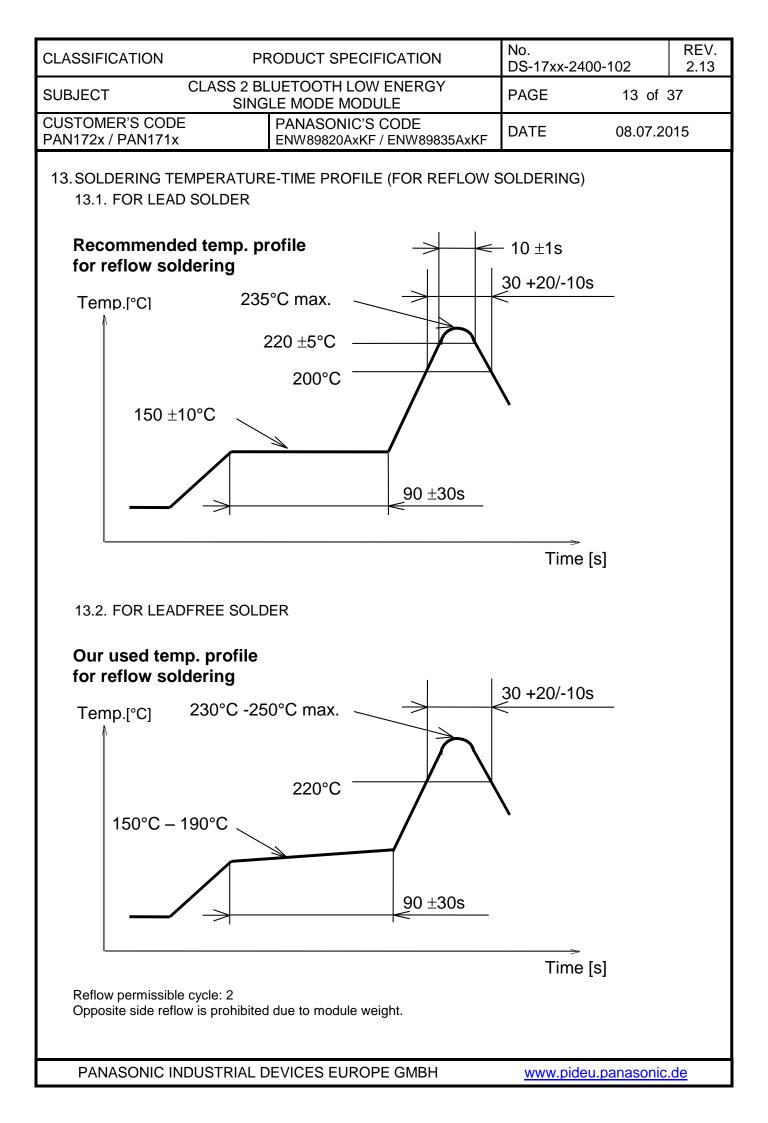
No	Characteristics	Condition	Min	Тур	Max	BT Spec	Unit
1	Operation frequency range		2402		2480		MHz
2	Channel spacing			2			MHz
3	Output Power	Maximum setting, measured at single ended 50ohm.		4			dBm
3		Minimum setting, measured at single ended 50ohm.		-24			dBm
4	Constitute Llink Opin Mode	High-gain mode		-93.0		-70	dDate
4	Sensitivity, High Gain Mode	Standard mode		-92.5		-70	dBm

12.2. PAN1721 BLUETOOTH CHARACTERISTICS

No	Characteristics	Condition	Min	Тур	Max	BT Spec	Unit
1	Operation frequency range		2402		2480		MHz
2	Channel spacing			2			MHz
2	Output Dower	Maximum setting, measured at single ended 500hm.		0			dBm
3	Output Power	Minimum setting, measured at single ended 500hm.		-24			dBm
4	Constitute Lligh Coin Mode	High-gain mode		-93.0		-70	dDm
4	Sensitivity, High Gain Mode	Standard mode		-92.5		-70	dBm

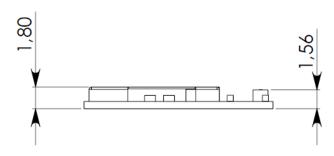
12.3. PAN17XX SPURIOUS EMISSION

No	Characteristics	Condition	Тур	Max	Unit
1	Spurious emissions	Conducted measurement with a $50-\Omega$ single-ended load. Complies with EN 300 328, EN 300 440 class 2, FCC CFR47, Part 15 and ARIB STD-T-66		-41	dBm



CLASSIFIC	CATION	PF	RODUCT SPEC	IFICATION	No. DS-17xx-24	00-102	REV. 2.13
SUBJECT	CL		LUETOOTH LO' LE MODE MOD		PAGE	14 of 3	37
CUSTOME PAN172x /			PANASONIC'S ENW89820AxK	S CODE F / ENW89835AxKF	DATE	08.07.20)15
14. PAN1 ⁻	72X MODULE	DIMENS	ION				
No.	Item	Dime	ension	Tolerance	Remark		
1	Width	8.70		± 0.20			

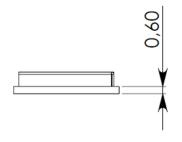
± 0.20



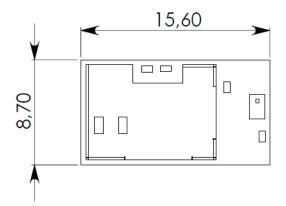
1.80

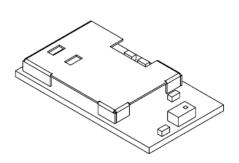
3

Height



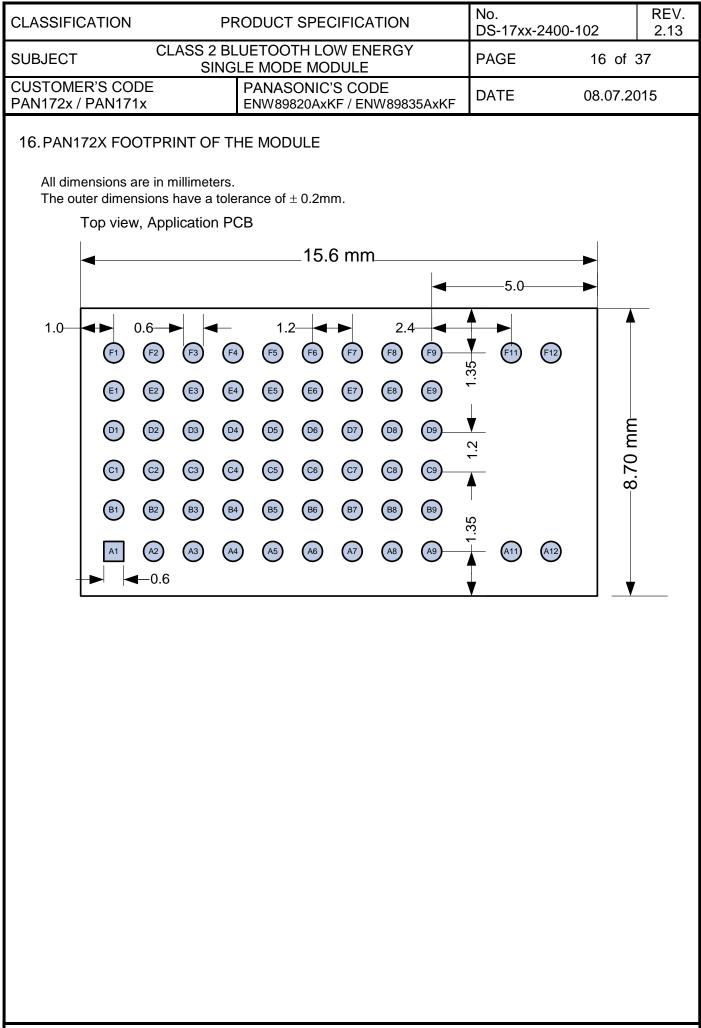
With case





SUBJECT CLASS 2 BLUETOOTH LOW ENERGY SINGLE MODE MODULE PAGE 15 of 37 CUSTOMER'S CODE PANASONIC'S CODE ENW89820AxKF / ENW89835AxKF DATE 08.07.2015 15.PAN171X DIMENSION 15.PAN171X DIMENSION 15.PAN171X DIMENSION 16.PANASONIC'S CODE ENW89820AxKF / ENW89835AxKF DATE 15.PAN171X DIMENSION 16.PANASONIC 10.20 17.PANASONIC 11.60 18.PANASONIC 10.20 19.PANASONIC With case		CATION	PR	ODUCT SPE	CIFICATION	No. DS-17xx-24	100-102	REV. 2.13
DAN172x / PAN171x ENW89820AxKF / ENW89835AxKF DATE 08.07.2015 15. PAN171X MODULE DIMENSION Item Dimension Tolerance Remark 1 Width 8.70 ± 0.20 Image: constraint of the second sec	SUBJECT	CL				PAGE	15 of 3	37
No. Item Dimension Tolerance Remark 1 Width 8.70 ± 0.20 1 2 Length 11.60 ± 0.20 1 3 Height 1.80 ± 0.20 With case						DATE	08.07.20	015
1 Width 8.70 ± 0.20 2 Length 11.60 ± 0.20 3 Height 1.80 ± 0.20 With case	15.PAN1	71X MODULE	DIMENSI	ON				
2 Length 11.60 ± 0.20 3 Height 1.80 ± 0.20 With case First Pin marking (made by Laser)	No.	Item	Dime	nsion	Tolerance	Remark		
3 Height 1.80 ± 0.20 With case	1	Width	8.70		± 0.20			
First Pin marking (made by Laser)	2	Length	11.60)	± 0.20			
First Pin marking (made by Laser)	3	Height	1.80		± 0.20	With case		
	1,8						1	

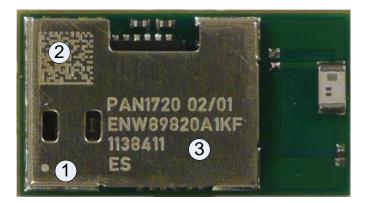
8,7



CLASSIFIC	CATION			PROD	UCT S	PECIF	ICATI	NC		No. DS-1	7xx-24	00-102	REV. 2.13
SUBJECT		CLA				I LOW MODL		GY		PAG	E	17 of	37
CUSTOME PAN172x /						NIC'S 0AxKF		9835A	xKF	DAT	E	08.07.2	015
17.PAN1	71X FO0	OTPRI	NT OF		IODUI	_E							
	ensions a ter dimen				e of ± 0).2mm.							
-	Top view, Application PCB												
	◀			1	1.6 r	nm							
1.0—		0.6—		<u> </u>	1.2								
1.0	F1	F2	F3	F4	(F5)	F 6	F7	F8	F9	22 22			
	E1	E2	E3	E4	E5	E6	E7	E8	E9	- 1.35-			
	01	D2	D3	D4	D 5	D6	D7	D 8	D9-	₹	- WW		
	C 1	C2	C 3	C4	C 5	C6	C7	C 8	C 9	 	8.70 mm		
	B1	B2	B3	B4	B5	B6	B7	B8	B9	.35			
	A1	A2	A3	A4	A5	(A6)	A7	A8	A9-				
_		€0.6								V	V	_	

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18.CASE MARKING



No.	Remark
1	Marking for Pin 1 (Circle 0,15 mm)
2	2D-Code, for internal usage only and can be change without any notice
3	Marking definition see below

18.1. EXAMPLE FOR MARKING

Ρ	Α	Ν	1	7	2	0			Η	W	/	S	W		
Е	Ν	W	8	9	8	2	0	Α	Х	Κ	F				
Υ	Υ	W	W	D	L	L									
F	С	С		D	•		Т	7	V	Ρ	Α	Ν	1	7	

18.2. MARKING DEFINITION

- (1) Pin1 marking
- (2) 2D code (Serial number)
- (3) Marking:
 - PAN17xx (Model Name), HW/SW (Hardware/Software version)
 - ENW89820AxKF (Part Number, refer to chapter 24 Ordering Information)
 - Lot code (YearYear, WeekWeek, Day, LotLot)
 - ES (Engineering Sample marking)

Note: For available Software Versions, refer to [1] PAN172xETU Design-Guide. and chapter 24 Ordering Information.

19. MECHANICAL REQUIREMENTS

No.	Item	Limit	Condition
1	Solderability	More than 75% of the soldering area shall be coated by solder	Reflow soldering with recommendable temperature profile
2	Resistance to soldering heat	It shall be satisfied electrical requirements and not be mechanical damage	See chapter 13.2

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SUBJECT		BLUETOOTH LOW ENER	GY	PAGE	19 of 3	37		
CUSTOMER PAN172x / F		PANASONIC'S CODE ENW89820AxKF / ENW8	9835AxKF	DATE	015			
20. DEVELOPMENT OF APPLICATIONS								
For deve	elopment support plea	se refer to [1] PAN172xETU D	esign-Guide					
21.RELIA	BILITY TESTS							
The mea	asurement should be o	done after being exposed to ro	om temperat	ure and humid	ity for 1 hour.			
No.	Item	Limit	Condition					
		Electrical parameter should be in	, ,	0Hz,Amplitude:1.5				

1	Vibration test	Electrical parameter should be in specification	 a) 20min. / cycle,1hrs. each of XYZ axis b) Freq.:30~100Hz, 6G b) 20min. / cycle,1hrs. each of XYZ axis
2	Shock test	the same as above	Dropped onto hard wood from height of 50cm for 3 times
3	Heat cycle test	the same as above	-40°C for 30min. and +85°C for 30min.; each temperature 300 cycles
4	Moisture test	the same as above	+60°C, 90% RH, 300h
5	Low temp. test	the same as above	-40°C, 300h
6	High temp. test	the same as above	+85°C, 300h

22. CAUTIONS

Failure to follow the guidelines set forth in this document may result in degrading of the product's functions and damage to the product.

22.1. DESIGN NOTES

- (1) Follow the conditions written in this specification, especially the control signals of this module.
- (2) The supply voltage has to be free of AC ripple voltage (for example from a battery or a low noise regulator output). For noisy supply voltages, provide a decoupling circuit (for example a ferrite in series connection and a bypass capacitor to ground of at least 47uF directly at the module).
- (3) This product should not be mechanically stressed when installed.
- (4) Keep this product away from heat. Heat is the major cause of decreasing the life of these products.
- (5) Avoid assembly and use of the target equipment in conditions where the products' temperature may exceed the maximum tolerance.
- (6) The supply voltage should not be exceedingly high or reversed. It should not carry noise and/or spikes.
- (7) Keep this product away from other high frequency circuits.

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22.2. INSTALLATION NOTES

- Reflow soldering is possible twice based on the conditions in chapter 15. Set up the temperature at the soldering portion of this product according to this reflow profile.
- (2) Carefully position the products so that their heat will not burn into printed circuit boards or affect the other components that are susceptible to heat.
- (3) Carefully locate these products so that their temperatures will not increase due to the effects of heat generated by neighboring components.
- (4) If a vinyl-covered wire comes into contact with the products, then the cover will melt and generate toxic gas, damaging the insulation. Never allow contact between the cover and these products to occur.
- (5) This product should not be mechanically stressed or vibrated when reflowed.
- (6) To repair the board by hand soldering, follow the conditions set forth in this chapter.
- (7) Do not wash this product.
- (8) Refer to the recommended pattern when designing a board.
- (9) Pressing on parts of the metal cover or fastening objects to the metal will cause damage to the unit.
- (10) For more details on LGA (Land Grid Arrey) soldering processes refer to the application note.

22.3. USAGE CONDITIONS NOTES

- (1) Take measures to protect the unit against static electricity. If pulses or other transient loads (a large load applied in a short time) are applied to the products, check and evaluate their operation befor assembly on the final products.
- (2) Do not use dropped products.
- (3) Do not touch, damage or soil the pins.
- (4) Follow the recommended condition ratings about the power supply applied to this product.
- (5) Electrode peeling strength: Do not add pressure of more than 4.9N when soldered on PCB.
- (6) Pressing on parts of the metal cover or fastening objects to the metal cover will cause damage.
- (7) These products are intended for general purpose and standard use in general electronic equipment, such as home appliances, office equipment, information and communication equipment.

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22.4. STORAGE NO	TES				
(2) Do not sto characteri • Storage	ore these istics of the in salty	I not be stressed mechanically duri products in the following conditions ne product, such as RF performanc air or in an environment with a high S, NH3, SO2, or NOX	s or the perfo e will be adv	versely affecte	

- Storage in direct sunlight
- Storage in an environment where the temperature may be outside the range of 5°C to 35°C range, or where the humidity may be outside the 45 to 85% range.
- Storage of the products for more than one year after the date of delivery Storage period: Please check the adhesive strength of the embossed tape and soldering after 6 months of storage.
- (3) Keep this product away from water, poisonous gas and corrosive gas.
- (4) This product should not be stressed or shocked when transported.
- (5) Follow the specification when stacking packed crates (max. 10).

22.5. SAFETY CAUTIONS

These specifications are intended to preserve the quality assurance of products and individual components.

Before use, check and evaluate the operation when mounted on your products. Abide by these specifications, without deviation when using the products. These products may short-circuit. If electrical shocks, smoke, fire, and/or accidents involving human life are anticipated when a short circuit occurs, then provide the following failsafe functions, as a minimum.

- (1) Ensure the safety of the whole system by installing a protection circuit and a protection device.
- (2) Ensure the safety of the whole system by installing a redundant circuit or another system to prevent a single fault causing an unsafe status.

22.6. OTHER CAUTIONS

- (1) This specification sheet is copyrighted. Please do not disclose it to a third party.
- (2) Please do not use the products for other purposes than those listed.
- (3) Be sure to provide an appropriate fail-safe function on your product to prevent an additional damage that may be caused by the abnormal function or the failure of the product.
- (4) This product has been manufactured without any ozone chemical controlled under the Montreal Protocol.
- (5) These products are not intended for other uses, other than under the special conditions shown below. Before using these products under such special conditions, check their performance and reliability under the said special conditions carefully to determine whether or not they can be used in such a manner.
 - In liquid, such as water, salt water, oil, alkali, or organic solvent, or in places where liquid may splash.
 - In direct sunlight, outdoors, or in a dusty environment
 - In an environment where condensation occurs.
 - In an environment with a high concentration of harmful gas (e.g. salty air, HCl,

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Cl2, SO2, H2S, NH3, and NOX)

(6) If an abnormal voltage is applied due to a problem occurring in other components or circuits, replace these products with new products because they may not be able to provide normal performance even if their electronic characteristics and appearances appear satisfactory.

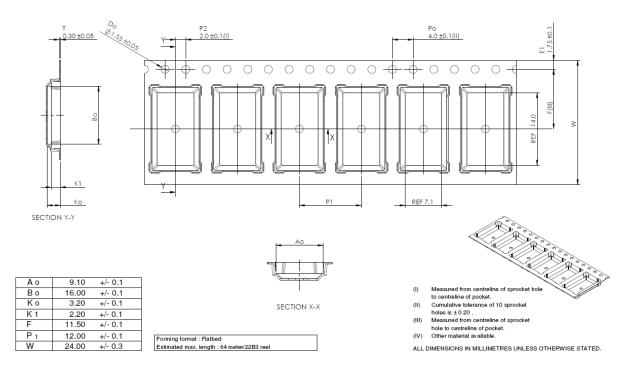
(7) When you have any question or uncertainty, contact Panasonic.

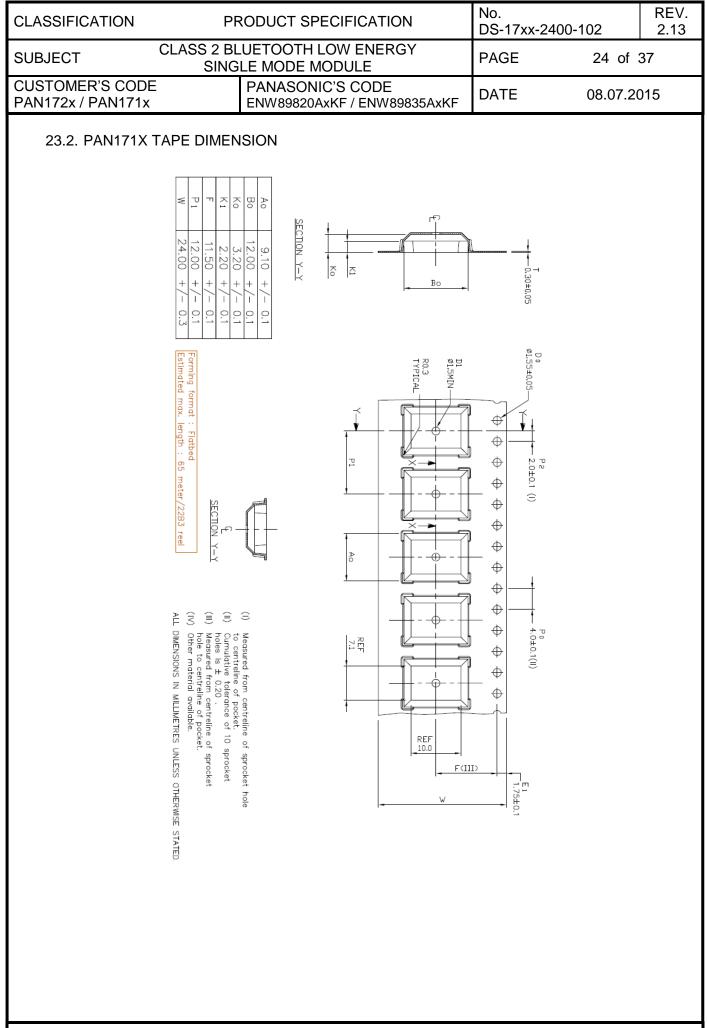
CLASSIFICATION	PF	RODUCT SPECIFICATION	No. DS-17xx-24	400-102	REV. 2.13
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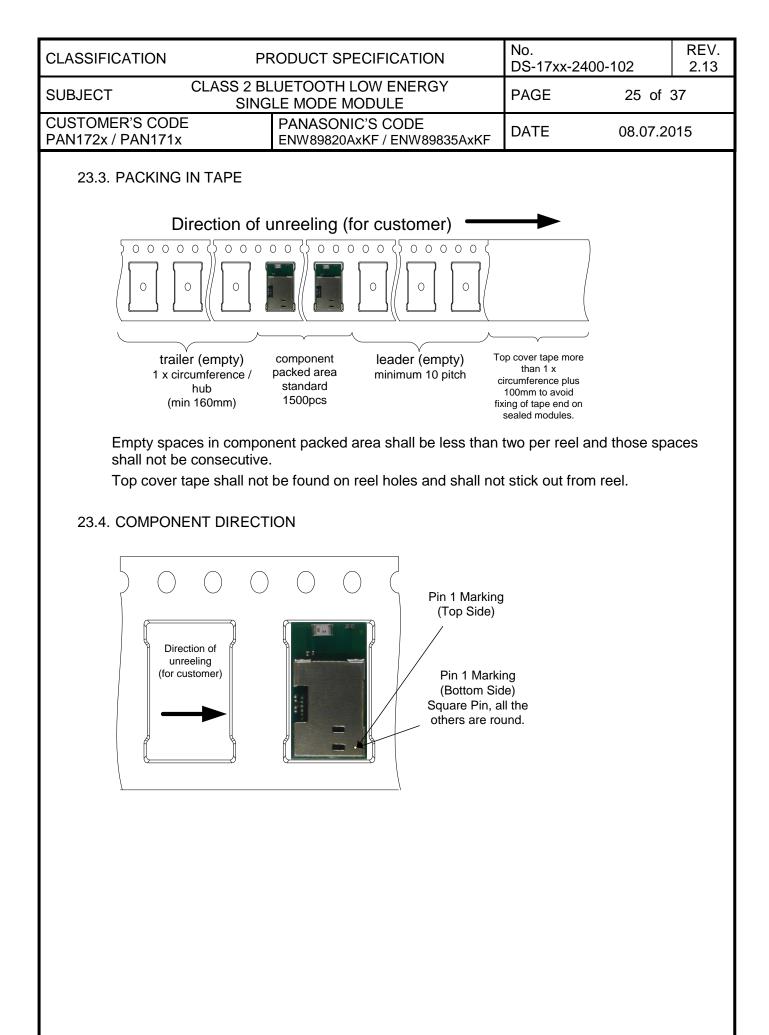
23. PACKAGING

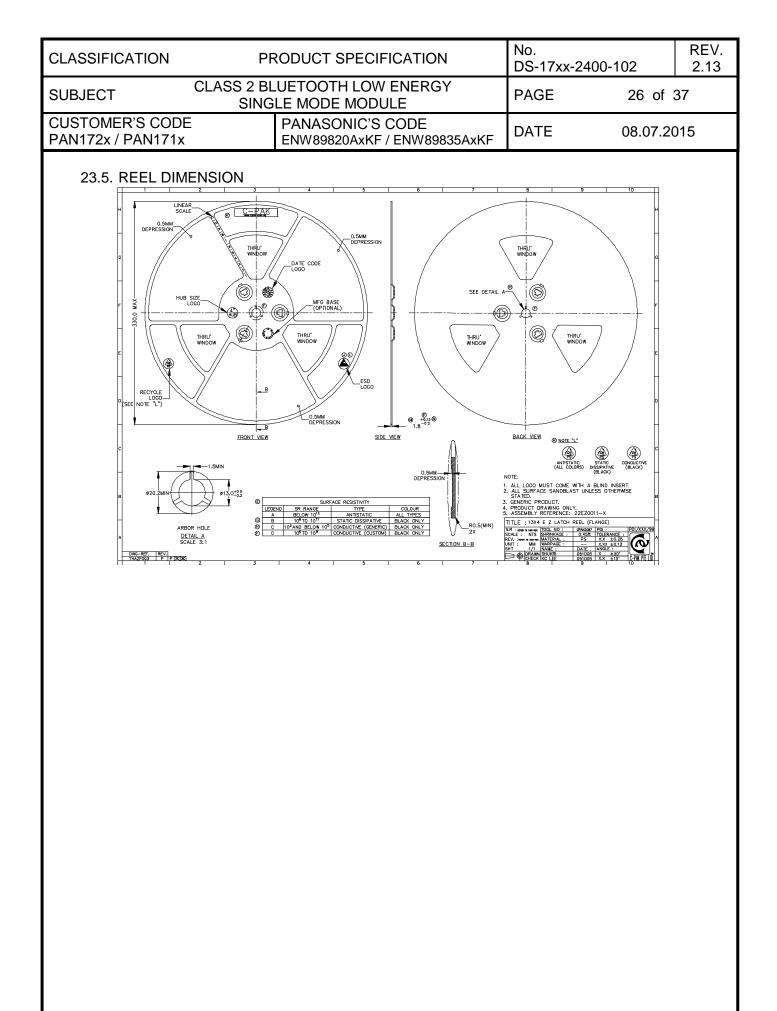
If the product has mass production status, indicated in chapter 26, we will deliver the module in the package which are described below.

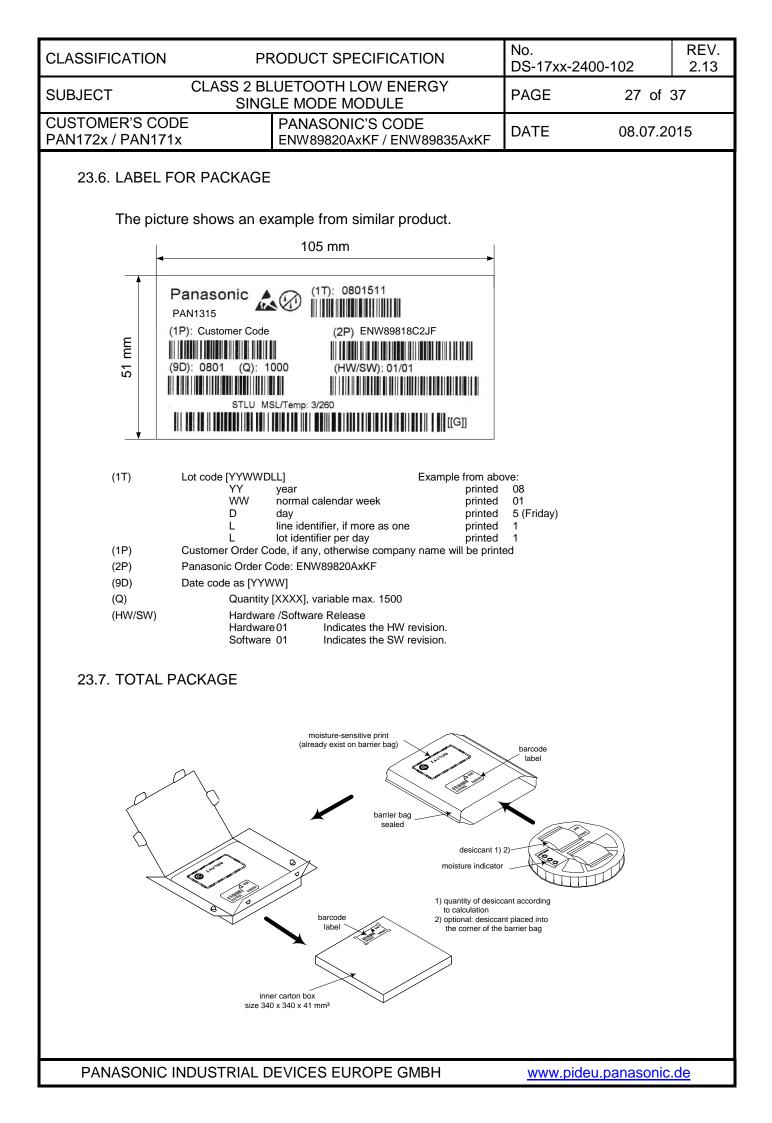
23.1. PAN172X TAPE DIMENSION











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24. ORDERING INFORMATION

Ordering part number	Description	MOQ ⁽¹⁾
	PAN1720	
ENW89820A1KF ⁽²⁾	CLASS 2 Bluetooth single mode Module according BT-4.0.	1500
	Bluetooth® smart device	
	PAN1720	
ENW89820A3KF ⁽²⁾	Same as above including BlueRadios BR-SPP FW version.	1500
	Bluetooth® smart device	
	PAN1721	
ENW89835A1KF ⁽²⁾	CLASS 2 Bluetooth single mode Module according BT-4.0.	1500
	Bluetooth® smart device	
	PAN1721	
ENW89835A3KF ⁽²⁾	Same as above including BlueRadios BR-SPP FW version.	1500
	Bluetooth® smart device	
	PAN1711	
ENW89835C1KF	CLASS 2 Bluetooth single mode Module according BT-4.0.	ES
	Bluetooth® smart device without antenna	
	PAN1711	
ENW89835C3KF	Same as above without antenna including BlueRadios BR-SPP FW version.	ES
	Bluetooth® smart device without antenna	

Notes:

- (1) Abbreviation for Minimum Order Quantity (MOQ). The standard MOQ for mass production is 1500 pieces, fewer only on customer demand. Samples for evaluation can be delivered at any quantity via the distribution channels.
- (2) Samples are available on customer demand

24.1. INFORMATION REGARDING SOFTWARE VERSIONS

ENW89820/35A1KF:

The modules will be delivered with an empty flash. Customers need to program their own TI software in the production process. For details refer to the design guide.

ENW89820/35A3KF:

The modules are delivered with BlueRadios nBlue software. This software includes a bootloade and can be updated over the UART. For the latest revision refer to this link: http://blueradios.com/panasonic/index.php

Note: New customers seeking firmware and firmware support are required to register by providing an invoice number.

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25. ROHS AND REACH D Hereby we declare to our follows th elatest official R	best present knov		declaration o	of our suppliers th	at this prod	uct
Harsa Gradi Tel: 9 Fax: 4	NORONIC NORM INDUITING DIVISION DI ALLA Ella 616 - 028 OS TRETTINA - 41210149 5469 300 - 44210149 5203 207					
Des	ar Customer			Date: 08.04.2015		
Pan	nasonic Industrial Devices	Slovakia s.r.o. guarantee	that:			
Din	ective 1907/2006 (REACH	<u>4)</u>				
pub abo Due this our <i>Pun</i> deli	betances from the candidat lished by ECHA are regu- lished by ECHA are regu- lished by ECHA are regu- lished to process required some fin- products base on informati- masonic Industrial Devices- livered to your company hav- <i>HC Substances:</i> SVHC Candidate list 1 SVHC Candidate list 2 SVHC Candidate list 3 SVHC Candidate list 3 SVHC Candidate list 3 SVHC Candidate list 4 SVHC Candidate list 5 SVHC Candidate list 5 SVHC Candidate list 6 SVHC Candidate list 6 SVHC Candidate list 7 SVHC Candidate list 7 SVHC Candidate list 8 SVHC Candidate list 8 SVHC Candidate list 9 SVHC Candidate list 9 SVHC Candidate list 10 SVHC Candidate list 10 SVHC Candidate list 11 SVHC Candida	these substance investigat these substance investigat ne. We will provide you v ian collected from our supp <i>Slovakia s.r.o.</i> hereby dee	ubstances are con- tions covering all o with all substance pliers. clares that all produ-	ntained in our products of our global suppliers, information regarding		
Dir	rective 2011/65/EC (RoHS		27000099-000-0150			
We	 confirm that all products ostances which are banned necentration of 0.1% by weig - Lead and lead compauds Mercury and mercury con - Chremium (VI), - PBB (phtybrominated bip 	supplied to you includin d by Directive 2011 65/J ght in homogeneous materi s, mpounds, Jacnyl) cutegory, PBDE (polybr tion of 0.01% by weight in hom	EC (RoHS) or if ials for: rominated hipbenyl et	f contain a maximum		
M	odel: Wireless Module	as (ENW898*, ENW5	96*, ENWC9A	*series)		
Create	c: Kostalikova Check	ik: Firmentova Viera		Bachsmann Udo		
EQ	still as	age TA	Managing Director	1500	-	

For the most updated one, please refer to [4].

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26. DATA SHEET STATUS

This data sheet contains the final specification (RELEASE).

Panasonic reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

Please consult the most recently issued data sheet before initiating or completing a design.

Use this URL to search for the most recent version of this data sheet:

PAN172x Datasheet

27. HISTORY FOR THIS DOCUMENT

Revision	Date	Modification / Remarks
0.01	November 2011	1 st preliminary version.
0.02	November 2011	Deleted footnote in chapter 11.
1.00	April 2012	Released Version.
1.1	July 2012	Add chapter 24.1 Information regarding Software Versions. Link to LGA app note. Removed watermark. UART pinning for BR-SW version. I2C pinning for PAN1721 version. FCC, IC, IDs.
1.2	July 2012	Added remark "top view" for footprint. Corrected FCC ID to T7VPAN17. Change to the correct company name in footer.
1.3	Agust 2012	Change IC text in chapter 32.1 Change to the correct company name in footer. New format for chapter Related Documents.
1.4	November 2012	Added some remarks to PAN1721 version. Added non antenna version part number to Ordering information.
1.5	December 2012	Added PAN1711 ES information.
1.6	January 2013	Added dimensions and pinout for the non-antenna versions PAN171x.
1.7	January 2013	Minor changes in chapter 6, 31.4. Chapter 3 was included and chapter 34 BT Certificiation was added.
1.8	May 2013	Changed Block Diagram.
1.9	August 2013	Included Crossreference for GPIOs to BlueRadios Pinout.
2.0	December 2013	Removed QDID from front page. QDID is described in chapter 33.
2.1	November 2014	Added radiation pattern for Antenna. Added DoC.
2.11	April 2015	Updated REACH RoHS.
2.12	July 2015	Correction of PAN1721 description.
2.13	June 2017	Correction of general description.

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28.REL/	ATED DOCUMENTS				
For a	an update, please search	in the suitable homepage.			
[1]	PAN172xETU Design-C	Guide onic.de/pdf/168ApplicationNote.pdf			
[2]	Semiconductor Datashe CC2540 from Texas Ins CC2541 from Texas Ins	struments			
[3]	Application Note Land (http://www.pideu.panas				
[4]	REACH and RoHS Cer http://www.pideu.panas	tificate onic.de/pdf/182ext2.jpg			

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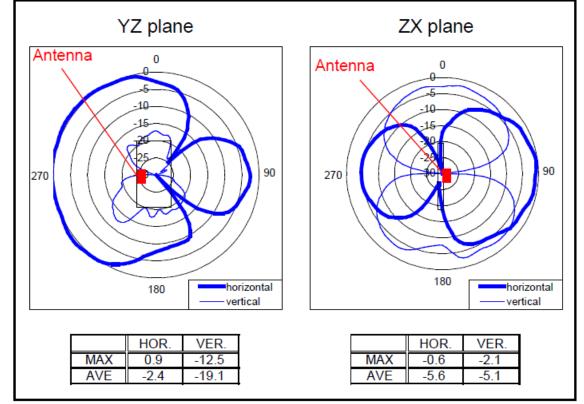
29. RADIATION PATTERN OF ANTENNA

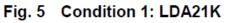
4.2 Antenna gain(3D measurement)

Table. 1 Condition 1: LDA21K

BT					[dBi]	[dB]
LINEA	R	YZ-p	olane	ZX-p	olane	Total
POLARIZA	TION	hor.	ver.	hor.	ver.	Efficiency
2400 MHz	MAX	-0.2	-14.8	-1.4	-3.3	
2400 10112	AVE	-3.3	-20.4	-6.4	-6.4	-3.1
2442 MHz	MAX	0.9	-12.5	-0.6	-2.1	
2442 11172	AVE	-2.4	-19.1	-5.6	-5.1	-2.2
2484 MHz	MAX	-0.4	-13.2	-1.9	-3.1	
	AVE	-3.4	-19.3	-6.8	-5.8	-3.2

4.3 Radiation Pattern(3D measurement)





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30. GENERAL INFORMATION

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This product description does not lodge the claim to be complete and free of mistakes. Please contact the related product manager in every case.

If we deliver ES samples to the customer, these samples have the status Engineering Samples. This means, the design of this product is not yet concluded. Engineering Samples may be partially or fully functional, and there may be differences to be published Data Sheet. Engineering Samples are not qualified and are not to be used for reliability testing or series production.

Disclaimer:

Customer acknowledges that samples may deviate from the Data Sheet and may bear defects due to their status of development and the lack of qualification mentioned above.

Panasonic rejects any liability or product warranty for Engineering Samples. In particular, Panasonic disclaims liability for damages caused by

- the use of the Engineering Sample other than for Evaluation Purposes, particularly the installation or integration in an other product to be sold by Customer,
- deviation or lapse in function of Engineering Sample,
- improper use of Engineering Samples.

Panasonic disclaimes any liability for consequential and incidental damages.

In case of any questions, please contact your local sales partner or the related product manager.

31. REGULATORY INFORMATION

31.1. FCC NOTICE



The devices PAN17xx, for details refer to Chapter 24, including the antennas, which are listed in 31.5, complies with Part 15 of the FCC Rules. The device meets the requirements for modular transmitter approval as detailed in FCC public Notice DA00-1407.transmitter Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation.

31.2. CAUTION



The FCC requires the user to be notified that any changes or modifications made to this device that are not expressly approved by Panasonic Industrial Devices Europe GmbH may void the user's authority to operate the equipment.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

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- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help

31.3. LABELING REQUIREMENTS



The Original Equipment Manufacturer (OEM) must ensure that FCC labeling requirements are met. This includes a clearly visible label on the outside of the OEM enclosure specifying the appropriate Panasonic FCC identifier for this product as well as the FCC Notice above. The FCC identifier is **FCC ID: T7VPAN17**. This FCC identifier is valid for all PAN17xx modules, for details, see the Chapter 24. Ordering Information.

In any case the end product must be labelled exterior with "Contains FCC ID: T7VPAN17"

31.4. ANTENNA WARNING



For the related part number of PAN17xx refer to Chapter 24. Ordering Information.

This devices are tested with a standard SMA connector and with the antennas listed below. When integrated in the OEMs product, these fixed antennas require installation preventing end-users from replacing them with non-approved antennas. Any antenna not in the following table must be tested to comply with FCC Section 15.203 for unique antenna connectors and Section 15.247 for emissions. The FCC identifier for this device with the antenna listed in item 1 are the same (FCC ID: T7VPAN17).

31.5. APPROVED ANTENNA LIST

Note: We are able to qualify your antenna and will add to this list as that process is completed.

Item	Part Number	Manufacturer	Frequency Band	Туре	Gain (dBi)
2	LDA212G3110K	Murata	2.4GHz	Chip-Antenna	+0.9

31.6. RF EXPOSURE PAN17XX



To comply with FCC RF Exposure requirements, the Original Equipment Manufacturer (OEM) must ensure that the approved antenna in the previous table must be installed.

The preceding statement must be included as a CAUTION statement in manuals for products operating with the approved antennas in the previous table to alert users on FCC RF Exposure compliance.

Any notification to the end user of installation or removal instructions about the integrated radio module is not allowed.

The radiated output power of PAN17xx with mounted ceramic antenna **(FCC ID: T7VPAN17)** is far below the FCC radio frequency exposure limits. Nevertheless, the PAN17xx shall be used in such a manner that the potential for human contact during normal operation is minimized.

End users may not be provided with the module installation instructions. OEM integrators and end users must be provided with transmitter operating conditions for satisfying RF exposure compliance.

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32. IND	USTRY CANADA (
	PAN17xx is licens license: IC: 216Q-		gulatory requ	irements of	Industry Ca	nada (IC),	
	Manufacturers of clarify any regulat Users can obtain This device has b a maximum gain o dBi are strictly pr ohms. The anter conjunction with a	mobile, fixed or p tory questions an Canadian informa een designed to o of 0.9 dBi. Antenn rohibited for use nna used for th	d ensure cor ation on RF ex operate with t as not include with this dev is transmitte	mpliance for xposure and the antenna ed in this lis rice. The re r must not	or SAR and/o d compliance as listed in T at or having a equired ante	or RF exposur e from <u>www.ic.</u> able 20 above a gain greater enna impedanc	re limits. . <u>gc.ca</u> . e, having than 0.9 ce is 50
	Due to the model not be displayed c	size the IC identi	ifier is display	/ed in the in			and can
32.1.	IC NOTICE The devices PAN in 31.5, complies modular tra Operation is subje interference, and interference	s with Canada R ansmitter ap ect to the followin d (2) This device	SS-GEN Rul oproval ng two condit ce must ac	les. The de as d ions: (1) Th	evice meets detailed his device m	the requirem in RS nay not cause e received, ir	ents for SS-GEN. harmful
32.2.	LABELING REQU The Original Equi met. This includes appropriate Panas identifier is 216Q- the Chapter 24. O In any case	ipment Manufactu s a clearly visible sonic IC identifier -PAN17. This IC i Ordering Informatic e the end	label on the r for this proc identifier is va	outside of t duct as well alid for all P	the OEM en II as the IC	nclosure specif Notice above. odules, for deta	ying the The IC ails, see
	"Contains IC: 216	Q-PAN17"					
33.BLU	ETOOTH CERTIFI	CATION					
	The Design is listen https://www.bluetoo	ed as Controller S oth.org/tpg/EPL_De	•)16552		
	The module is list	ted as EPL based	on Texas In:	struments C	DID B0165	52.	
	To create an EPL need to be combi	_, two Subsystems ined.	3 e.g. QDID: I	3016552 an	าd QDID: B0	17183 (softwa	re stack)

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34. EUROPEAN R&TTE DEC	claration of confoi		DoC)		
	1999/5/	'EC			
We, Panasonic Industrial I	Devices Europe GmbH		43		
Wireless Connectivity	, Power Electronics R&D Center				
Zeppelinstrasse 19, 2	337 Lueneburg, Germany				
declare under our sole respon	sibility that the product:				
Type of equipment: Blue	tooth Module				
Brand name: PAN	1720 PAN1721 PAN1710 PAN171	1			
		12			
	V89820AxKF ENW89820CxKF EN Software Version (BlueRadios/TI)	W89835AxKF ENW8	9835CxKF		
	fortware version (Directaulos 11)				
	tes, is in compliance with all the a isions of the European Council D	Contraction of the second s			
1999/5/EC	Radio and Telecommunica	tions Terminal Equipme	nt Directive (R&TTE)		
The conformity assessment p	rocedure used for this declaration	is Annex IV of this	Directive.		
	demonstrated on the basis of:			22	
- EN 60950-1: 2006+A11:200 - EN 62311:2008 - EN 62479: 2010	09+A1:2010+A12:2011+A2:2013	For article 3.1a: Saf	ety/Health		
- EN 301 489-17 V2.2.1:2012	-09	For article 3.1b: Ele	: Electromagnetic Compatibility		
- EN 300 328 V1.8.1:2012-06		For article 3.2: Radi	0		
The technical contruction file	is kept available at:	- No-			
20-1-1-20-00-00-00-00-00-00-00-00-00-00-00-00-	rrope GmbH, Zeppelinstrasse 19, 21	337 Lueneburg, Germ	any		
Issued on:	2014-11-19				
Signed by the manufacturer:					
(Company name)	Panasonic Industrial Devic	es Europe GmbH			
(Signature)	Pul yours	M C M II 2014			
(Printed name)	0 Peter Jeroschewski	~			
(Title)	General Manager	Power Electronics R	&D Center		

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As a result of the conformity assessment procedure described in Annex III of the Directive 1999/5/EC, the end-customer equipment should be labelled as follows:

C€

PAN17xx and their versions in the specified reference design can be used in the following countries: Austria, Belgium, Cyprus, Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Poland, Portugal, Slovakia, Slovenia, Spain, Sweden, The Netherlands, the United Kingdom, Switzerland, and Norway.

35. LIFE SUPPORT POLICY

This Panasonic product is not designed for use in life support appliances, devices, or systems where malfunction can reasonably be expected to result in a significant personal injury to the user, or as a critical component in any life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness. Panasonic customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Panasonic for any damages resulting.

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Click to view products by Panasonic manufacturer:

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